

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
□	8.0	+3.0/-8.0	PLATED	2105
•	12.0	+3.0/-12.0	PLATED	2100
•	12.01	+3.0/-12.01	PLATED	63
•	14.0	+3.0/-3.0	PLATED	32
•	20.0	+3.0/-3.0	PLATED	14
◦	28.0	+3.0/-3.0	PLATED	84
◊	36.0	+3.0/-3.0	PLATED	4
△	38.0	+3.0/-1.0	PLATED	22
◦	40.0	+2.0/-2.0	PLATED	24
◦	42.0	+3.0/-3.0	PLATED	22
□	45.0	+3.0/-3.0	PLATED	35
◦	50.0	+3.0/-3.0	PLATED	6
A	63.0	+3.0/-3.0	PLATED	4
B	90.0	+3.0/-3.0	PLATED	2
C	126.0	+3.0/-3.0	PLATED	4
D	157.0	+3.0/-3.0	PLATED	4
F	52.0	+3.0/-3.0	NON-PLATED	2
E	59.0	+3.0/-3.0	NON-PLATED	4
G	67.008	+3.0/-3.0	NON-PLATED	1
H	147.008	+3.0/-3.0	NON-PLATED	2



0.197

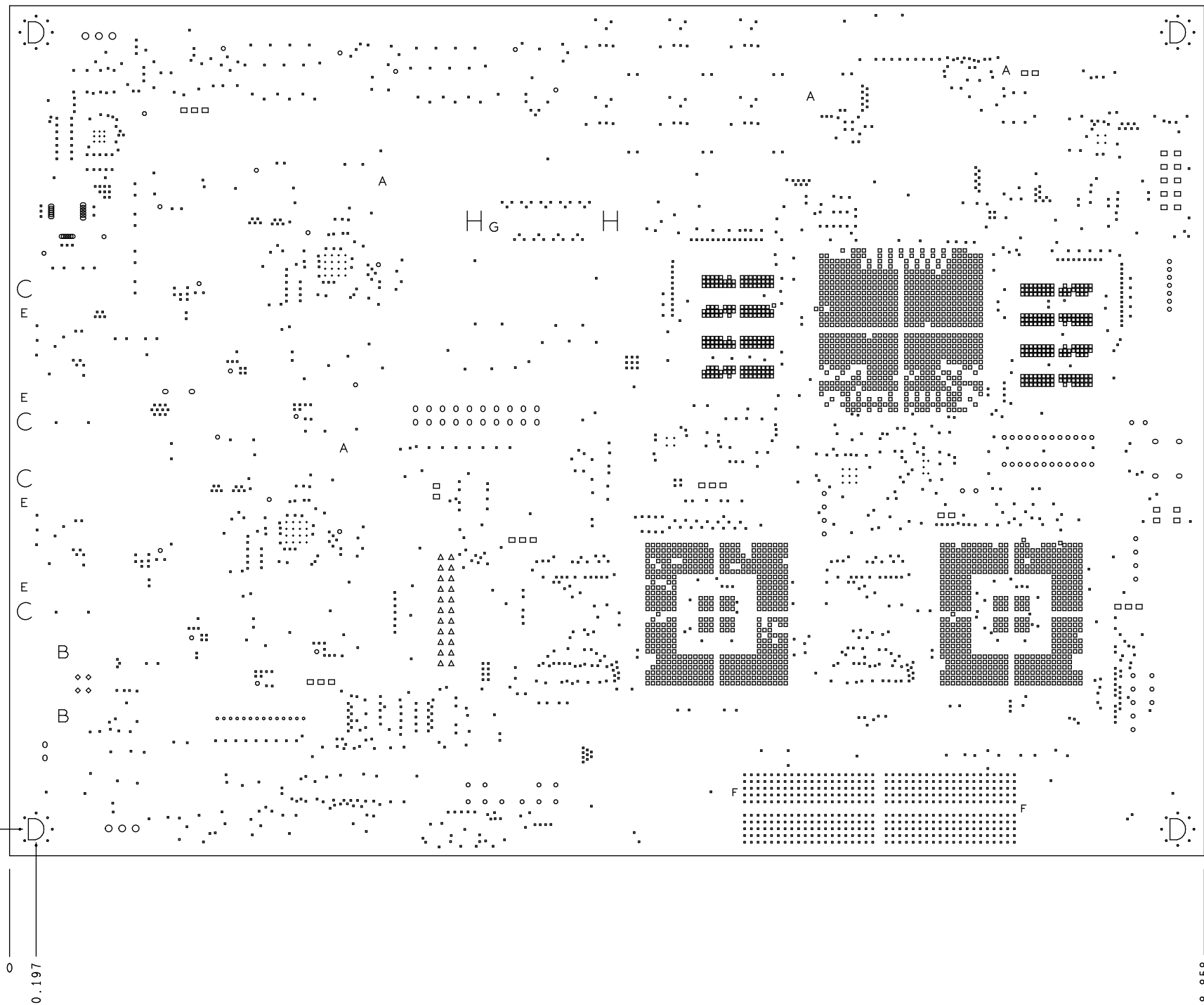
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Primary Side Shown

TEXAS INSTRUMENTS		
BOARD NAME:	DLP072-DLPC4420AEVMX	DESCRIPTION: FAB DRAWING
PROJECT #:	DLP-30341-04	DATE: 22 AUG 2023 REVISION:



8.858

- FAB NOTES:
- ALL DIMENSIONS ARE IN INCHES. UNLESS OTHERWISE SPECIFIED, ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
 - THE PWB SHALL BE FABRICATED TO IPC-6011 AND IPC-6012, CLASS 2, TYPE 3. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
 - BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT. ROHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. ROHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
 - ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER.
 - MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH WITH A MINIMUM ANNULAR RING OF .001 INCH.
 - OVERALL BOARD THICKNESS TO BE .070 +/- .005 AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
 - INNER PLANE LAYERS TO BE 1 OZ. COPPER. INNER SIGNAL LAYERS TO BE 1/2 OZ COPPER. OUTER LAYERS TO BE 1/2 OZ. COPPER + PLATING.
 - MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
 - ALL HOLES ARE ON A 0.0001 GRID EXCEPT THOSE INDICATED.
 - MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
 - NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
 - FOIL OUTER OPTIONAL.
 - INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994
 - TEARDROP VIAS AS NECESSARY.
 - THIEVING IS NOT ALLOWED.
- PROCESS NOTES:
- EXCEPT AS NOTED BELOW, ALL EXPOSED CONDUCTORS ON BOTH SIDES PWB SHALL BE ELECTROPLATED GOLD (5-15 MICROINCHES) OVER ELECTROPLATED NICKEL (150 MIN MICROINCHES).
 - APPLY LPI OR LDI SOLDERMASK. COLOR: BLUE. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
 - FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
 - APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK BOTH SIDES. COLOR: WHITE.
 - BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
 - ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94-V0 REGISTERED MATERIAL ID NUMBER.
- FILL 12.01 VIAS W/NON-CONDUCTIVE EPOXY AND POLISH FLAT SUITABLE FOR SOLDERING

LAYER STACKUP	
LAYER 1 - PRIMARY SIDE	
LAYER 2 - GND PLANE	
LAYER 3 - SIGNAL	
LAYER 4 - GND PLANE	
LAYER 5 - SIGNAL	EXTERNAL LAYERS
LAYER 6 - GND PLANE	0.005" WIDE 50 OHMS SINGLE ENDED +/-10%
LAYER 7 - PWR PLANE	0.0038" WIDE/0.0062" SPACING 100 OHMS DIFFERENTIAL +/-10%
LAYER 8 - PWR PLANE	0.0045" WIDE/0.0055" SPACING 90 OHMS DIFFERENTIAL +/-10%
LAYER 9 - GND PLANE	INTERNAL LAYERS
LAYER 10 - SIGNAL	0.004" WIDE 50 OHMS SINGLE ENDED +/-10%
LAYER 11 - GND PLANE	0.0035" WIDE/0.0065" SPACING 100 OHMS DIFFERENTIAL +/-10%
LAYER 12 - SIGNAL	0.00425" WIDE/0.00575" SPACING 90 OHMS DIFFERENTIAL +/-10%
LAYER 13 - GND PLANE	
LAYER 14 - SIGNAL	